



PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:

Larry D. Kinsman

Serial No.: 10/792,229

Filed: March 3, 2004

For: BUMPED DIE AND WIRE BONDED
BOARD-ON-CHIP PACKAGE

Confirmation No.: 4782

Examiner: T. Ho

Group Art Unit: 2818

Attorney Docket No.: 2269-4585.3US
(00-658.03/US)

CERTIFICATE OF MAILING

I hereby certify that this correspondence along with any attachments referred to or identified as being attached or enclosed is being deposited with the United States Postal Service as First Class Mail on the date of deposit shown below with sufficient postage and in an envelope addressed to the Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

September 1, 2005
Date


Signature

Leta M. Howard
Name (Type/Print)

RESPONSE

Mail Stop Amendment
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Examiner:

This communication is in response to the Office Action of June 2, 2005 whose initial period of response is set to expire on September 2, 2005.

A listing of claims begins on page 2 of this paper.

Remarks begin on page 8 of this paper.

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